

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

<b>Applicant(s):</b>	Stephen W. Bedell, et al.	<b>Examiner:</b>	Unassigned
<b>Serial No:</b>	Unassigned	<b>Art Unit:</b>	Unassigned
<b>Filed:</b>	Herewith	<b>Docket:</b>	YOR920010499682US2 (14710A)
<b>For:</b>	METHOD OF CREATING HIGH-QUALITY RELAXED SiGe-ON-INSULATOR FOR STRAINED Si CMOS APPLICATIONS	<b>Dated:</b>	April 14, 2004

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT**

Sir:

In accordance with 37 C.F.R. §§ 1.97 and 1.98, it is requested that the following references, which are also listed on the attached Form PTO-1449, be made of record in the above-identified case.

1. U.S. Patent No. 5,461,243, dated October 24, 1995, issued to Ek, et al.;
2. U.S. Patent No. 5,563,428, dated October 8, 1996, issued to Ek, et al.;

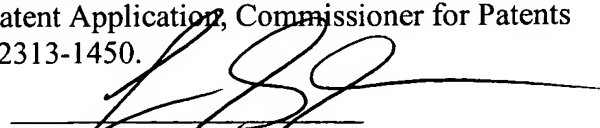
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**CERTIFICATE OF MAILING BY EXPRESS MAIL**

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I hereby certify that this correspondence is being deposited with the United States Postal Service Express Mail Post Office to Addressee service under 37 C.F.R. §1.10 on the date indicated above and is addressed to the Mail Stop Patent Application, Commissioner for Patents and Trademarks, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: April 14, 2004

  
Leslie S. Szivos, Ph.D.

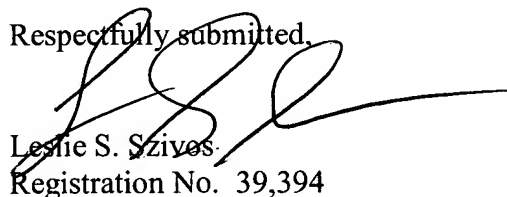
3. U.S. Patent No. 5,667,586, dated September 16, 1997, issued to Ek, et al.;
4. U.S. Patent No. 5,759,898, dated June 2, 1998, issued to Ek, et al.;
5. U.S. Patent No. 5,846,867, dated December 8, 1998, issued to Gomi, et al.;
6. U.S. Patent No. 6,190,975 B1, dated February 20, 2001, issued to Kubo, et al.;
7. U.S. Patent No. 4,866,498, dated September, 1998, issued to Myers;
8. U.S. Patent No. 6,118,151 A, dated September, 2000, issued to Tsutsu;
9. U.S. Publication No. 2002/0030227, dated March, 2002, issued to Bulsara, et al.; and
10. U.S. Patent No. 6,515,335 B1, dated February, 2003, issued to Christiansen, et al.

Pursuant to 37 C.F.R. §1.98(d), copies of the above listed references are not provided, as the references were previously submitted to the Examiner or cited by the Examiner in connection with parent case, U.S. Serial Number: 10/055,138 filed on January 23, 2002.

Consideration of this Information Disclosure Statement is respectfully requested.

Inasmuch as this Information Disclosure Statement is being submitted in accordance with the schedule set out in 37 C.F.R §1.97(b), no statement or fee is required.

Respectfully submitted,



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Form PTO-1449 U.S. DEPARTMENT OF COMMERCE (REV. 7-80) PATENT AND TRADEMARK OFFICE  <b>INFORMATION DISCLOSURE CITATION</b>  <i>(Use several sheets if necessary)</i>				<b>Atty. Docket No. (Optional)</b>  14710A		<b>Application Number</b>  Unassigned	
				<b>Applicant(s)</b> Stephen W. Bedell, et al.			
				<b>Filing Date</b> April 14, 2004		<b>Group Art Unit</b> Unassigned	
<b>U.S. PATENT DOCUMENTS</b>							
<b>EXAMINER INITIAL*</b>		<b>DOCUMENT NUMBER</b>	<b>DATE</b>	<b>NAME</b>	<b>CLASS</b>	<b>SUBCLASS</b>	<b>FILING DATE (if appropriate)</b>
	1.	5,461,243	10/24/1995	Ek, et al.			
	2.	5,563,428	10/8/1996	Ek, et al.			
	3.	5,667,586	9/16/1997	Ek, et al.			
	4.	5,759,898	6/2/1998	Ek, et al.			
	5.	5,846,867	12/8/1998	Gomi, et al.			
	6.	6,190,975 B1	2/20/2001	Kubo, et al.			
	7.	4,866,498	9/1998	Myers			
	8.	6,118,151 A	9/2000	Tsutsu			
	9.	2002/0030227	3/2002	Bulsara, et al.			
	10.	6,515,335 B1	2/2003	Christiansen, et al.			
<b>FOREIGN PATENT DOCUMENTS</b>							
	<b>REF</b>				<b>CLASS</b>	<b>SUBCLASS</b>	<b>TRANSLATION</b>
							YES NO
<b>OTHER DOCUMENTS</b> <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>							
<b>EXAMINER</b>				<b>DATE CONSIDERED</b>			
* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							